



## Florida CirTech - Lab Capabilities

Standard product testing and lab analysis is shown in the table below

Products	Standard Product Tests
<b>CP155</b>	Sulfuric acid % by vol., Copper Sulfate g/L, Chloride ppm, CP155 % by volume, Hull Cell
<b>CT160</b>	Catalyst Normality, Stannous Chloride g/L, Color Standard, Copper g/L
<b>CT164</b>	Catalyst Normality, Stannous Chloride g/L, Color Standard, Copper g/L
<b>CT300</b>	Palladium ppm, Copper ppm, Sulfuric Acid % by volume
<b>EN300</b>	Nickel g/L, Reducer g/L, Sodium Orthophosphite g/L
<b>IG300</b>	Copper ppm, Nickel ppm, Gold g/L, IG300 % by volume
<b>IS150 Pre-dip</b>	Acid Normality, IS150B % by volume, IS150B UV-Vis % by volume
<b>IS150</b>	Silver g/L, Copper g/L, Acid Normality, IS150B UV-Vis % by volume, IS150B % by volume
<b>SP130</b>	Sulfuric Acid % by volume, Stannous Tin g/L, Hull Cell, SP130 % by volume
<b>TS14</b>	S.G., Normality, Copper ppm
<b>TS28</b>	S.G., Normality, Stannous Tin g/L, Visual, OMIKRON Coupon Test, Thiourea, Copper, Beta Factor

## Additional Tests

### AAS Solder analysis:

The flame AA can measure metals in solution such as: tin, lead, copper, zinc, gold, nickel, and iron. The minimum detection limit on our equipment is generally 1.0 ppm. Our equipment has both acetylene / air and acetylene / nitrous oxide flame capability.

### SERA tin / solder thickness:

Measures thickness of pure tin and the copper-tin intermetallic layer for both immersion tin coatings and solder coatings on circuit boards. The SERA also has the capability to measure tin oxides on these coatings.

### Arc Spark OES metal analysis:

The arc spark can measure metal content of tin based solder samples. It is programmed to measure silver, aluminum, arsenic, gold, bismuth, cadmium, copper, iron, indium, nickel, lead, antimony, zinc, germanium and tin.

### Hull cell testing:

If a customer is seeing a plating issue they can send in a sample and the lab can run plating tests to recreate and resolve the issue being seen. Our Hull cell capabilities include copper and tin plating solutions.

### Solder pot with SN100C alloy:

Small lab scale solder pot can be used for solderability float and dip testing.

